Search History

L	Hits	Search Text	DB	Time stamp
Number		4430/11		0004/00/01
-	112	(438/11).CCLS.	USPAT; US-PGPUB; EPO; JPO;	2004/09/01 17:06
_	1508	(438/14).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/16 19:21
-	668	(438/15).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/16 19:21
-	450	(438/18).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/16 19:22
-	109	calibration with substrate and metrology	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/16
-	45	calibration with substrate and metrology and calibration with layer	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/08/16 19:23
	1	calibration with substrate and metrology and calibration with layer and rms	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/16 19:23
-	6	calibration with substrate and metrology and calibration with layer and root	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/08/30 06:07
_	9	calibration near layer and rms	IBM_TDB USPAT; US-PGPUB; EPO; JPO;	2004/09/06 03:04
-	4	calibration near layer same (silicon adj dioxide or halfnium adj dioxide or aluminum adj dioxide or tantalum adj dioxide or halfnium adj silicate or zicronium adj silicate or zicronium adj	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/30 06:18
_	15	oxide) calibration near layer and metrology	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/06 03:04
-	1	"5851842".PN.	IBM_TDB USPAT	2004/08/30
-	915	(438/16).CCLS.	USPAT; US-PGPUB; EPO; JPO;	2004/09/06 03:01
_	3675	(438/17).CCLS.	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/09/06 03:01
L			IBM TDB	

_	8	calibra\$4 with layer and rms and	USPAT;	2004/09/06
i		metrology	US-PGPUB;	03:05
			EPO; JPO;	
			DERWENT;	
İ			IBM_TDB	
-	102	calibra\$4 with layer and rms	USPAT;	2004/09/06
			US-PGPUB;	03:05
			EPO; JPO;	l
			DERWENT;	]
			IBM_TDB	
1	1628	438/778	USPAT;	2004/09/06
			US-PGPUB;	03:11
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	1
2	1213	438/787	USPAT;	2004/09/06
			US-PGPUB;	03:11
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	